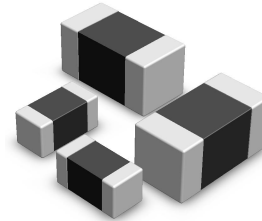


Surface Mount Multilayer Varistor

SV0603N300G0A

Description

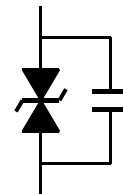
The SV0603N300G0A is based on Multilayer fabrication technology. These components are designed to suppress a variety of transient events, including those specified in IEC 61000-4-2 or other standards used for Electromagnetic Compliance (EMC). The SV0603N300G0A is typically applied to protect integrated circuits and other components at the circuit board level. It can operate over a wider temperature range than zener diodes.



Features

- ◆ SMD type zinc oxide based ceramic chip
- ◆ Lead free plating termination provided good solderability characteristic
- ◆ Insulator overcoat keeps excellent low and stable leakage current
- ◆ Quick response time (<1ns)
- ◆ Low clamping voltage
- ◆ High transient current capability
- ◆ Meet IEC 61000-4-2 standard
- ◆ Compact size for EIA 0603

Equivalent Circuits



Applications

- ◆ Application for Mother Board, Notebook, Cellular Phone, PDA, handheld device, DSC, DV, Scanner, and Set-Top Box...etc.
- ◆ Suitable for Push-Button, Power Line and Low Frequency single line over-voltage protect.

Surface Mount Multilayer Varistor

SV0603N300G0A

Electrical Characteristics (25±5°C)

Symbol	Minimum	Typical	Maximum	Units
V_{RMS}	—	—	21	V
V_{DC}	—	—	30	V
V_V	36	—	45	V
V_C	—	—	99	V
I_{max}	—	—	30	A
W_{max}	—	—	0.1	J

V_{RMS} - Maximum AC operating voltage the varistor can maintain and not exceed 10μA leakage current.

V_{DC} - Maximum DC operating voltage the varistor can maintain and not exceed 10μA leakage current.

V_V - Voltage across the device measure at 1mA DC current.

Equivalent to V_B "breakdown voltage".

V_C - Maximum peak current across the varistor with 8/20μs waveform and 1A pulse current.

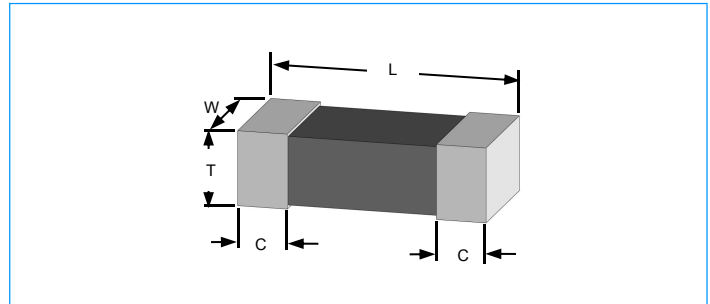
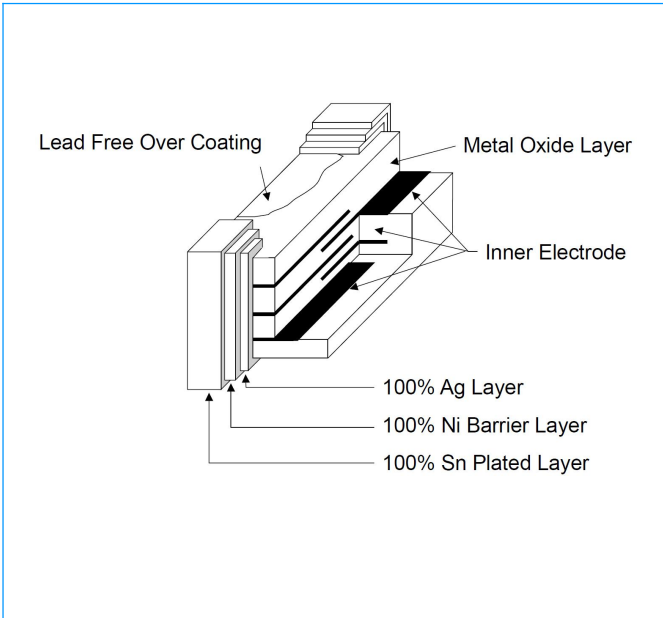
I_{max} - Maximum peak current which may be applied with 8/20μs waveform without device failure.

W_{max} - Maximum energy which may be dissipated with the 10/1000μs waveform without device failure.

Surface Mount Multilayer Varistor

SV0603N300G0A

Construction & Dimensions



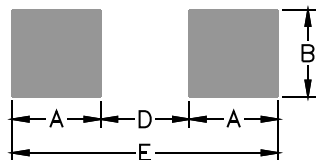
Size EIA (EIAJ)	0603 (1608)	
Symbol	Inches	Millimeters
L	0.063±0.006	1.60±0.15
W	0.031±0.004	0.80±0.10
T	0.031±0.008	0.80±0.20
C	0.012±0.008	0.30±0.20

Pad Layouts & Precaution for handling of substrate

Solder cream in reflow soldering

Refer to the recommendable land pattern as printing mask pattern for solder cream.

(1) Print solder in a thickness of 150 to 200µm



Precaution for handling of substrate

Do not exceed to bend the board after soldering this product extremely. (reference examples)

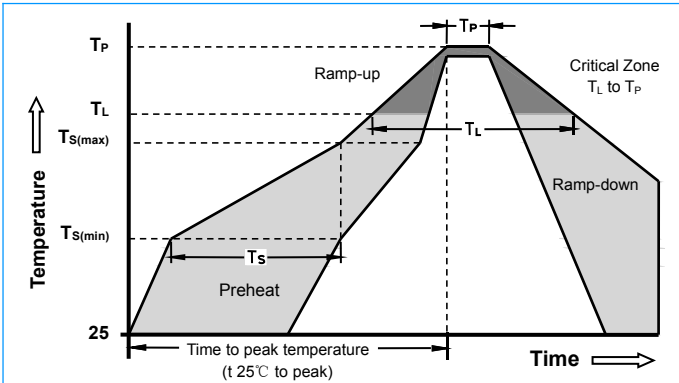
- Mounting place must be as far as possible from the position, which is close to the break line of board or on the line of large holes of board.
- Do not bend extremely the board, in mounting another component. If necessary, use back-up pin (support pin) to prevent from bending extremely.
- Do not break the board by hand. We recommend to use the machine or the jig to break it.

Size EIA (EIAJ)	0603 (1608)	
Symbol	Inches	Millimeters
A	0.040	1.02
B	0.030	0.76
D	0.020	0.50
E	0.100	2.54

Surface Mount Multilayer Varistor

SV0603N300G0A

Soldering Parameters



Precaution for Soldering

Note that this product will be easily damaged by rapid heating, rapid cooling or local heating.

Do not give heat shock over 100°C in the process of soldering. We recommend to take preheating and gradual cooling

Soldering gun procedure

Note the follows, in case of using solder gun for replacement.

- 1) The tip temperature must be less than 280 for the period within 3 seconds by using soldering gun under 30W
- 2) The soldering gun tip shall not touch this product directly.

Soldering volume

Note that excess of soldering volume will easily get crack the body of this product.

Reflow Condition		Pb-Free assembly
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max ($T_{s(max)}$)	+200°C
	-Time (min to max) (T_s)	60 - 180 Seconds
Average ramp up rate (Liquidus Temp T_L) to peak		3°C/Second Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/Second Max
Reflow	- Temperature (T_L) (Liquidus)	+217°C
	- Time (min to max) (T_L)	60 - 150 Seconds
Peak Temperature (T_P)		260 +0/-5°C
Time within 5°C of actual peak Temperature (T_P)		20-40 Seconds
Ramp-down Rate		6°C/Second Max
Time 25°C to peak Temperature (T_P)		8 minutes Max

General Technical Data

Operating Temperature		-40 ~ +85°C
Storage Temperature		-40 ~ +85°C
Response Time		<1 ns
Solderability		245±5°C, 3±1sec
Solder leach resistance		260±5°C, 10±1sec
Taping Package Storage Condition	Storage Temperature	5 ~ 40°C
	Relative Humidity	To 65%
	Storage Time	12 Months max

Environmental Performance

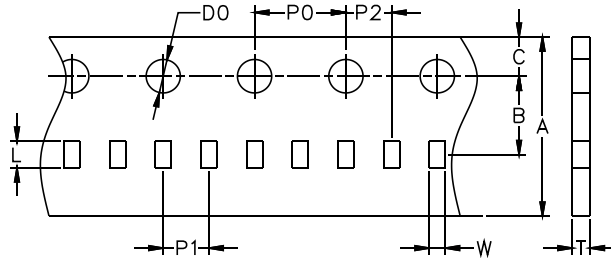
Item	Specifications	Test Condition
Bias Humidity	$\Delta V_V / V_V \leq \pm 10 \%$	90%RH, 40°C, Working Voltage, 1000 hrs
Thermal Shock	$\Delta V_V / V_V \leq \pm 10 \%$	-40°C to 85°C, 30 min. cycle, 5 cycles
Full Load Voltage	$\Delta V_V / V_V \leq \pm 10 \%$	Working Voltage, 85°C, 1000 hrs

Surface Mount Multilayer Varistor

SV0603N300G0A

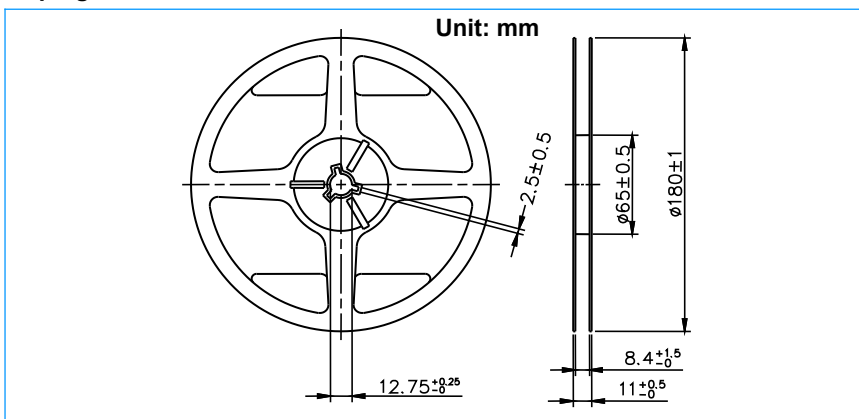
Packaging Information

Carrier Tape Dimensions



Size EIA (EIAJ)	0603 (1608)	
Symbol	Inches	Millimeters
A	0.315±0.012	8.00±0.30
B	0.138±0.002	3.50±0.05
C	0.069±0.002	1.75±0.10
D0	0.061±0.002	1.55±0.05
P0	0.157±0.004	4.00±0.10
P1	0.079±0.002	4.00±0.10
P2	0.079±0.002	2.00±0.05
W	0.041±0.006	1.05±0.15
L	0.075±0.006	1.90±0.15
T	0.037±0.002	0.95±0.05

Taping Reel Dimensions



Taping Specifications

There shall be the portion having no product in both the head and the end of taping, and there shall be the cover tape in the heat of taping.

Quantity of products in the taping package

SIZE EIA (EIAJ)	0603 (1608)
Standard Packing Quantity (PCS / reel)	4,000

The contents of a box :

0603 Series: 6 reels / inner box